

# **Himalaya DC Charger Power Module**

## **Power Module Assembly Document**

**Document Number**

**TBD**

**Revision -Draft**

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# INDEX

| <b>Sr. No</b> | <b>Particulars</b>            | <b>Page No.</b> |
|---------------|-------------------------------|-----------------|
| <b>1</b>      | <b>INTRODUCTION</b>           | <b>3</b>        |
| <b>2</b>      | <b>STEPS FOR POM ASSEMBLY</b> | <b>4</b>        |

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| 1.0                          | POWER MODULE FCT Rev01 | Omprakash              | Shiva                  | 8/02/2025   |

# **1. INTRODUCTION**

## **1.1 Purpose**

The purpose of this document is to describe the steps for PoM assembly into single package (Box) after LV FCT test for High voltage power testing.

## **1.2 Scope of this document**

Power Module Packaging includes following items:

- Power Board 1 (PB1)
- Power Board 2 (PB2)
- Gate Driver Board Primary (GDB1)
- Gate Driver Board Secondary (GDB2)
- One Board to board connector.
- Power cable
- Heat sinks quantities (PB1- 3, PB2- 4 (Primary side -2 & secondary side-2)
- Enclosure
- Top & Bottom insulation sheet
- Heat sinks insulation Sheets!
- Thermal Pad (sheets) For PB1-3 & PB2-4 Quantities
- NTC- PB1-1 Quantity & PB2-2 Quantities with connector
- FAN assembly with Connectors.
- Short pins (black color)

**2-SOP for PoM assembly follows these steps in sequence**

**1)- PB1 & PB2 Enclosure Should be available.**



**2)-Fix Black color insulation sheets in PB1 & PB2 enclosure.**



**3)-Put PB1 & PB2 In enclosure including insulation sheets and fix it with screws**

**(SCREW Spring and flat Washer M4\*8 ZN K-PZ)**

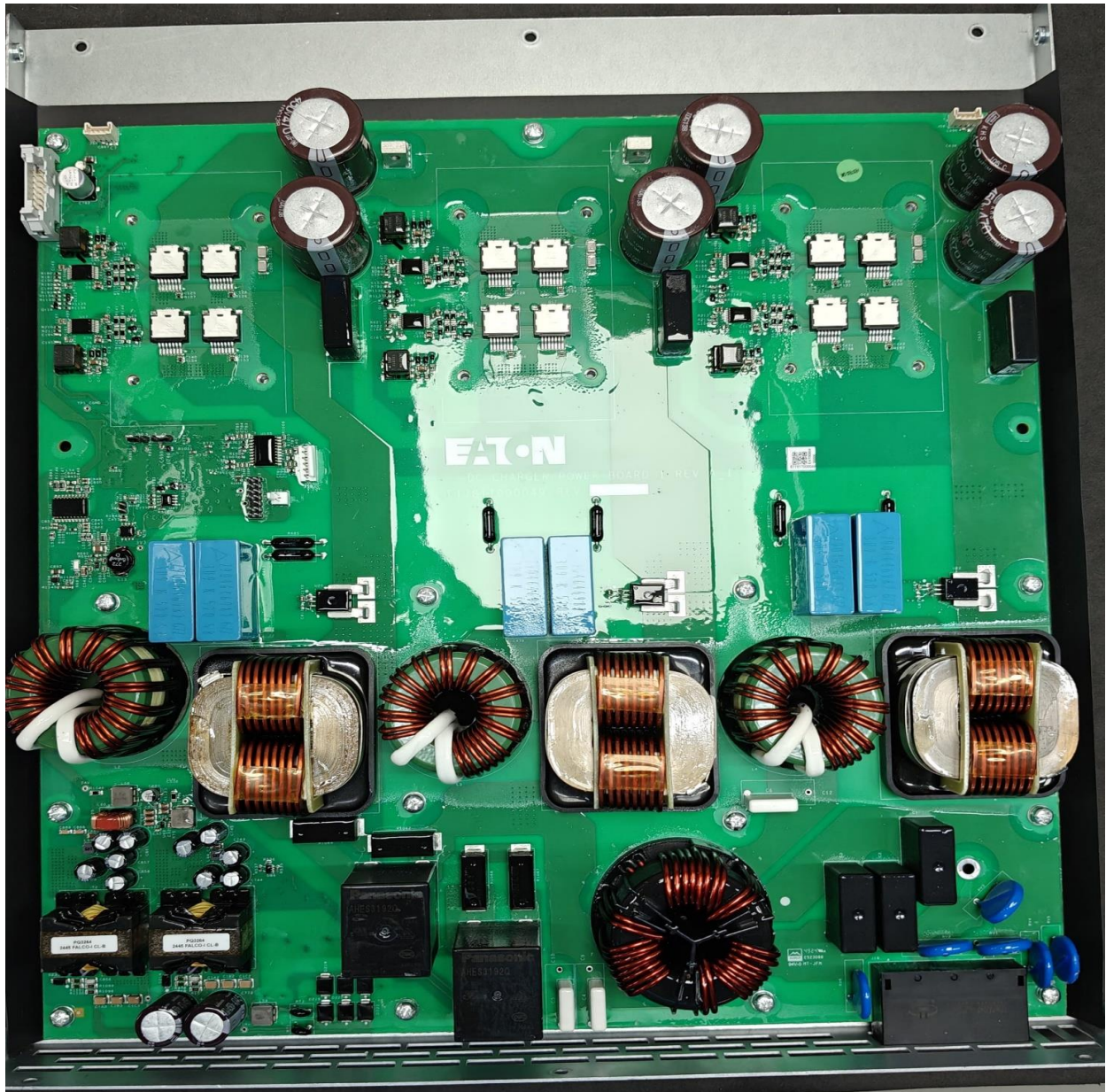


**PB2**



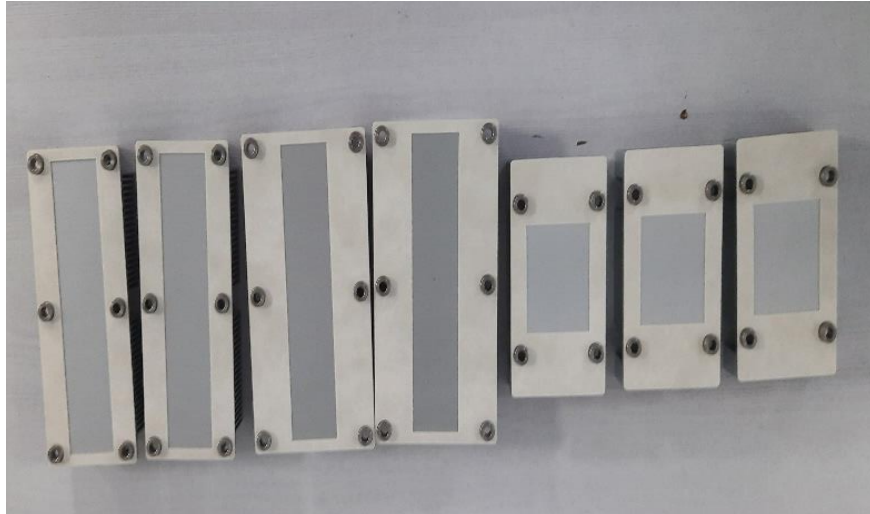
**PB1**



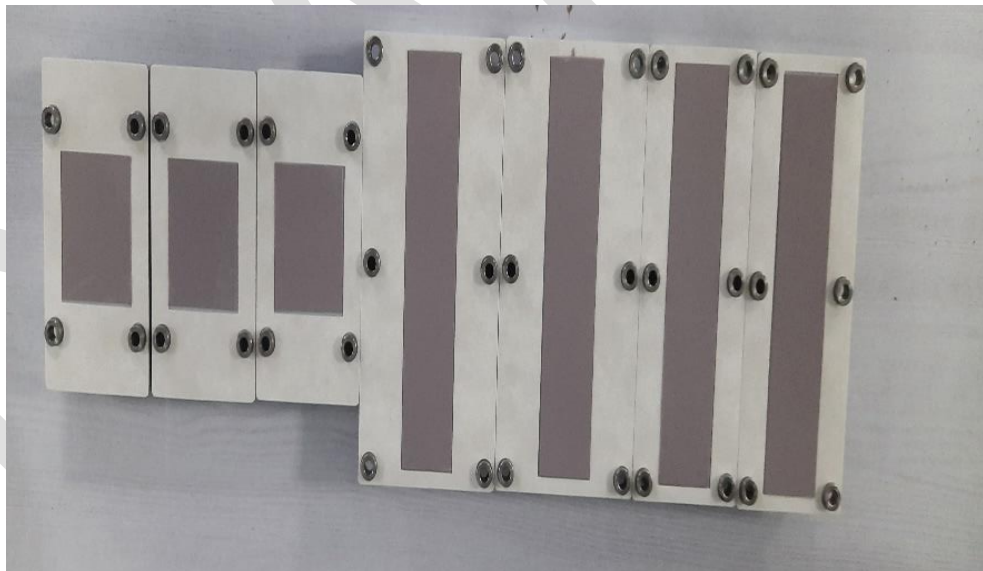


**4)-Prepare Heat Sinks for PB1 & PB2 Mosfets in following manner:**

#### **4.1-Paste White color insulation sheets on heat sink.**



#### **4.2-Place Thermal pad on heat sinks**

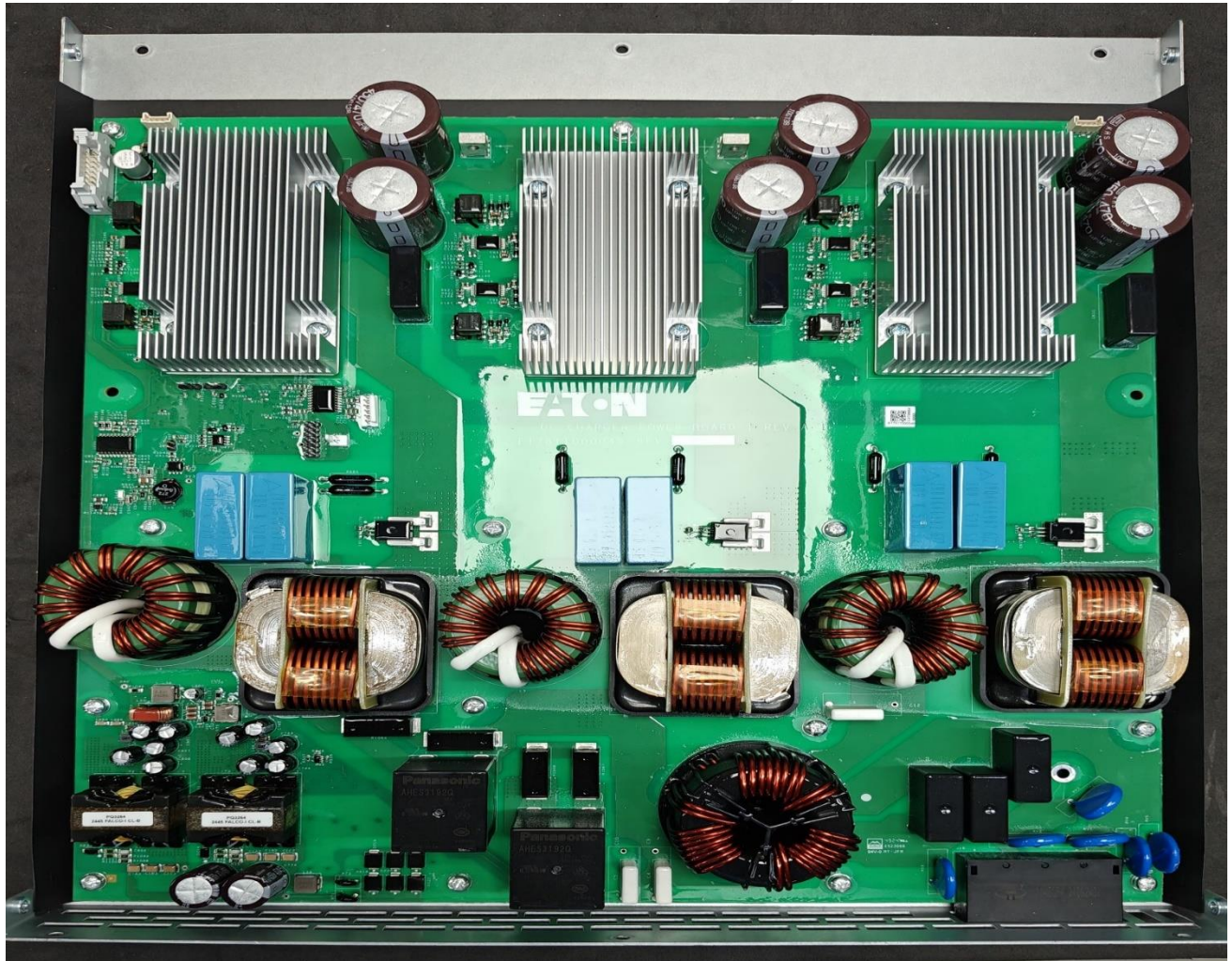


#### **5)-Place Heat Sinks on PB1 & PB2 and tight it with screws and ensure that screws should not be loosed. (SCREW, Spring and Flat WASHER M4\*15 TRUSS CROSS ZN)**



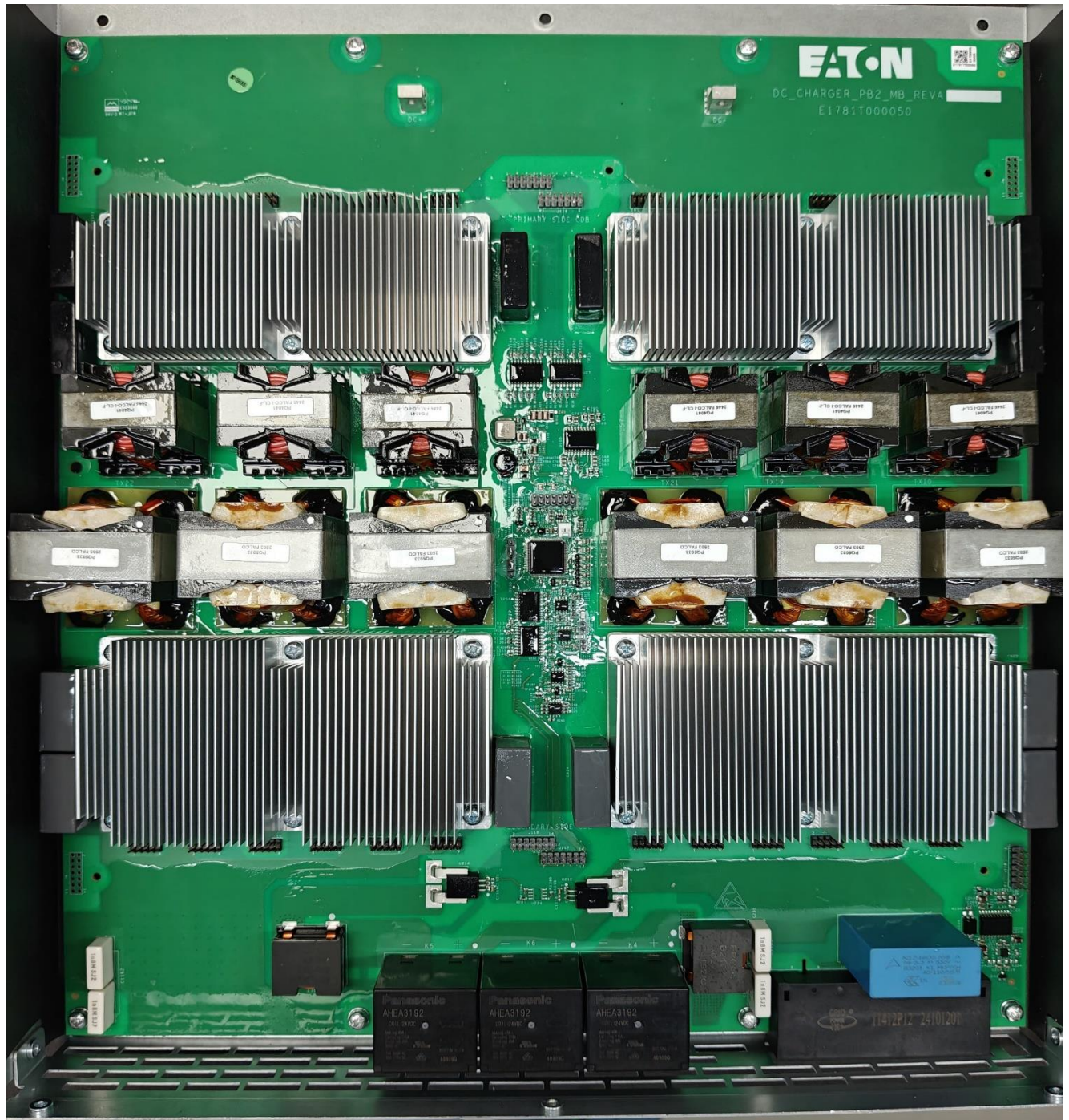


**PB1**



**PB2**





**PB1 & PB2 after placing all screws.**

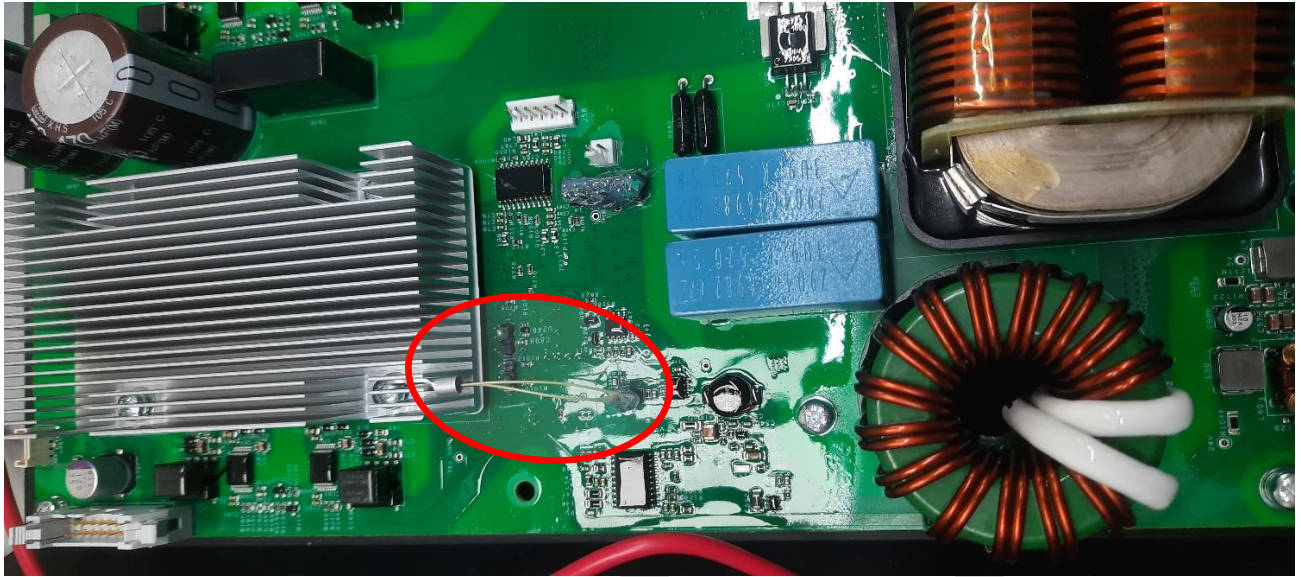




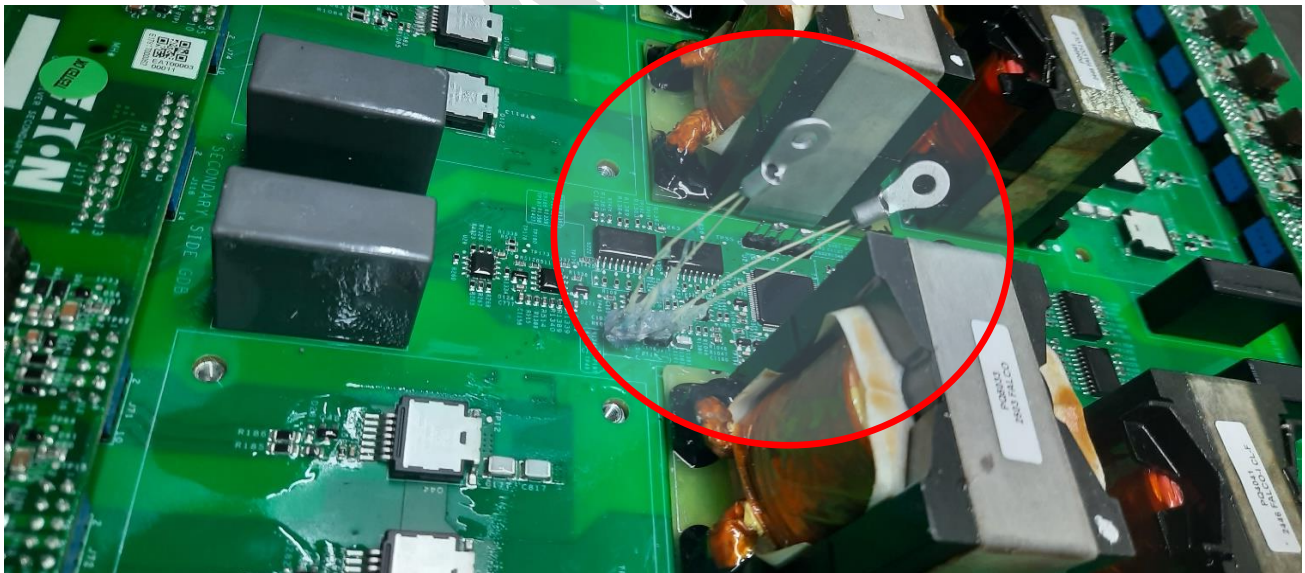
**6)-Place NTCs on PB1 (One quantity) & PB2 (2 quantities) Heat Sinks. After placing put the glue**

**PB1-J41 Connector**





**PB2- J41 & J62 Connector**



**7)-Start packing PB1 & PB2 by overlapping on each other and placing screws (M4\*8 Flat Zn Blue Pre-Glue D7)**



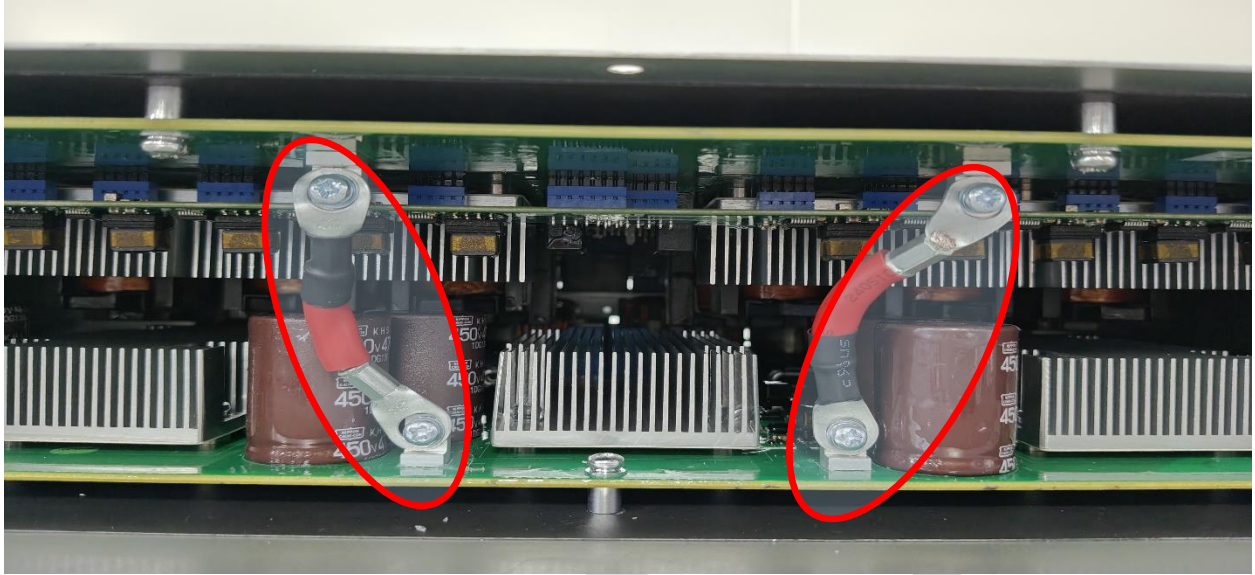


**8)-Place board to board connector mentioned in red portion.**





**9)-Place power cable (10 sq mm with lugs) mentioned in below image.**



10)- Place FAN Assembly by connecting connectors (**RED wire -4 pin, black wire-3 pin & brown wire-2 pin of connector**) & ensure connectors intact should not be loose (Put Glue at connectors)

